

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-11 (Canceled)

Claim 12 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode ~~formed~~ at the first surface of the semiconductor element;

a wiring portion ~~formed~~ on the first surface of the semiconductor element and connected to the electrode;

a conductive post ~~formed~~ on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer ~~formed~~ on the first surface of the semiconductor element, the resin layer covers so as to cover the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection ~~formed~~ on the conductive post; and

a protective layer ~~formed~~ on the second surface of the semiconductor element,

wherein an end portion of the protective layer is aligned with both an end portion of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer, the semiconductor element and the resin layer define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape comprised of a hardened synthetic resin achieving a bonding function that bonds the tape to the second surface of the semiconductor element.

Claim 13 (Canceled)

Claim 14 (Currently Amended): A semiconductor device according to claim 12, wherein the ~~protective layer~~ tape comprises a polyimide or an epoxy resin.

Claim 15 (Previously Presented): A semiconductor device according to claim 12, wherein the external connection is a solder ball.

Claim 16 (Previously Presented): A semiconductor device according to claim 12, wherein the conductive post is comprised of copper.

Claim 17 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first

surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode ~~formed~~ at the first surface of the semiconductor element;

a wiring portion ~~formed~~ on the first surface of the semiconductor element and connected to the electrode;

a conductive post ~~formed~~ on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer ~~formed~~ on the first surface of the semiconductor element, the resin layer covers so as to cover the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection ~~formed~~ on the conductive post; and

a protective layer ~~formed~~ on the second surface of the semiconductor element, wherein a side surface of the semiconductor element is exposed from the resin layer and the protective layer, wherein an end portion of the protective layer is aligned with both the exposed side surface of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer and the resin layer, and the exposed side surface of the semiconductor element define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape which comprises a hardened synthetic resin ~~achieving a bonding function~~ that bonds the tape to the second surface of the semiconductor element.

Claim 18 (Canceled)

Claim 19 (Currently Amended): A semiconductor device according to claim 17, wherein the ~~protective layer~~ tape comprises a polyimide or an epoxy resin.

Claim 20 (Previously Presented): A semiconductor device according to claim 17, wherein the external connection is a solder ball.

Claim 21 (Previously Presented): A semiconductor device according to claim 17, wherein the conductive post is comprised of copper.

Claim 22 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode ~~formed~~ at the first surface of the semiconductor element;

a wiring portion ~~formed~~ on the first surface of the semiconductor element and connected to the electrode;

a conductive post on the first surface of the semiconductor element, the conductive post having a first end portion connected to the wiring portion and a second end portion~~[[,]] and being formed on the first surface of the semiconductor element, the~~

~~first end portion of the conductive post being connected to the wiring portion;~~

a resin layer ~~formed~~ on the first surface of the semiconductor element, the resin layer covers so as to cover the first surface of the semiconductor element, the wiring portion and a side of the conductive post, and wherein the second end portion of the conductive post is not ~~[[being]]~~ covered by the resin layer;

an external connection ~~formed~~ on the second end portion of the conductive post;
and

a protective layer ~~formed~~ on the second surface of the semiconductor element,
wherein only a side surface of the semiconductor element is exposed from the resin layer and the protective layer, wherein an end portion of the protective layer is aligned with both the side surface of the semiconductor element and an end portion of the resin layer, and wherein the end portions of the protective layer and the resin layer, and the side surface of the semiconductor element define an outer edge of the semiconductor device, and

wherein the protective layer is a peelably removable UV sensitive tape which comprises a hardened synthetic resin ~~achieving a bonding function~~ that bonds the tape to the second surface of the semiconductor element.

Claim 23 (Canceled)

Claim 24 (Currently Amended): A semiconductor device according to claim 22, wherein the protective-layer tape comprises a polyimide or an epoxy resin.

Claim 25 (Previously Presented): A semiconductor device according to claim 22, wherein the external connection is a solder ball.

Claim 26 (Previously Presented): A semiconductor device according to claim 22, wherein the conductive post is comprised of copper.

Claim 27 (Currently Amended): A semiconductor device, comprising:

a semiconductor element having a first surface and a second surface, the first surface being an opposite surface with respect to the second surface of the semiconductor element;

an electrode ~~formed~~ at the first surface of the semiconductor element;

a wiring portion ~~formed~~ on the first surface of the semiconductor element and connected to the electrode;

a conductive post ~~formed~~ on the first surface of the semiconductor element and connected to the wiring portion;

a resin layer ~~formed~~ on the first surface of the semiconductor element, the resin layer covers so as to cover the first surface of the semiconductor element, the wiring portion and a side of the conductive post;

an external connection terminal ~~formed~~ on the conductive post; and
a protective layer ~~formed~~ on the second surface of the semiconductor element,
wherein a side surface of the protective layer is in a same plane with both a side
surface of the semiconductor element and a side surface of the resin layer, and wherein
the side surfaces of the protective layer, the semiconductor element and the resin layer
define an outer edge of the semiconductor device, and
wherein the protective layer is a peelably removable UV sensitive tape
comprised of a hardened synthetic resin ~~achieving a bonding function that bonds the~~
tape to the second surface of the semiconductor element.

Claim 28 (Canceled)

Claim 29 (Currently Amended): A semiconductor device according to claim 27, wherein
the ~~protective layer~~ tape comprises a polyimide or an epoxy resin.

Claim 30 (Previously Presented): A semiconductor device according to claim 27,
wherein the external connection terminal is a solder ball.

Claim 31 (Previously Presented): A semiconductor device according to claim 27,
wherein the conductive post is comprised of copper.